

MOSFETs Silicon N-channel MOS (U-MOSVII-H)

TPH4R50ANH

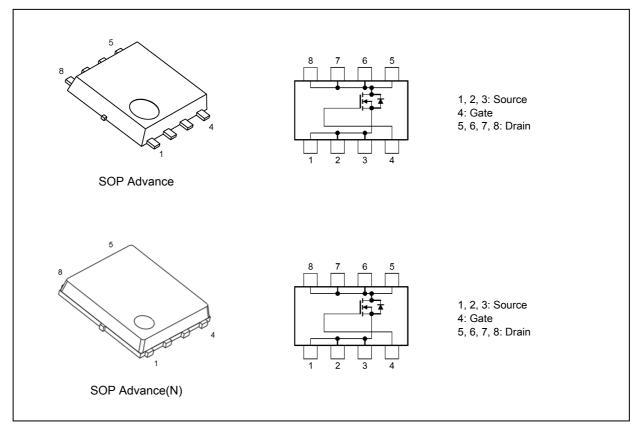
1. Applications

- · DC-DC Converters
- Switching Voltage Regulators
- · Motor Drivers

2. Features

- (1) Small, thin package
- (2) High-speed switching
- (3) Small gate charge: $Q_{SW} = 22 \text{ nC (typ.)}$
- (4) Low drain-source on-resistance: $R_{DS(ON)} = 3.7 \text{ m}\Omega$ (typ.) ($V_{GS} = 10 \text{ V}$)
- (5) Low leakage current: $I_{DSS} = 10 \mu A \text{ (max)} \text{ (V}_{DS} = 100 \text{ V)}$
- (6) Enhancement mode: $V_{th} = 2.0$ to 4.0 V ($V_{DS} = 10$ V, $I_D = 1.0$ mA)

3. Packaging and Internal Circuit



The package can be selected according to your preference. For details, please contact your TOSHIBA sales representative.

Start of commercial production



4. Absolute Maximum Ratings (Note) (Ta = 25°C unless otherwise specified)

Characteristic	cs		Symbol	Rating	Unit
Drain-source voltage			V _{DSS}	100	V
Gate-source voltage			V _{GSS}	±20	
Drain current (DC)	(Silicon limit)	(Note 1), (Note 2)	I _D	93	Α
Drain current (DC)	(T _c = 25°C)	(Note 1)	I _D	60	
Drain current (pulsed)	(t = 1 ms)	(Note 1)	I _{DP}	200	
Power dissipation	(T _c = 25°C)		P_D	78	W
Power dissipation	(t = 10 s)	(Note 3)	P_D	2.8	W
Power dissipation	(t = 10 s)	(Note 4)	P_{D}	1.6	W
Single-pulse avalanche energy		(Note 5)	E _{AS}	274	mJ
Avalanche current			I _{AR}	60	Α
Channel temperature			T _{ch}	150	ů
Storage temperature	-	-	T _{stg}	-55 to 150	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

5. Thermal Characteristics

Character	istics		Symbol	Max	Unit
Channel-to-case thermal resistance	(T _c = 25°C)		R _{th(ch-c)}	1.60	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 3)	R _{th(ch-a)}	44.6	°C/W
Channel-to-ambient thermal resistance	(t = 10 s)	(Note 4)	R _{th(ch-a)}	78.1	°C/W

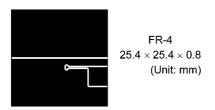
Note 1: Ensure that the channel temperature does not exceed 150°C.

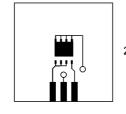
Note 2: Limited by silicon chip capability. Package limit is 60 A.

Note 3: Device mounted on a glass-epoxy board (a), Figure 5.1

Note 4: Device mounted on a glass-epoxy board (b), Figure 5.2

Note 5: V_{DD} = 60 V, T_{ch} = 25°C (initial), L = 0.082 mH, R_{G} = 1.0 Ω , I_{AR} = 60 A





 $\begin{aligned} & \text{FR-4} \\ 25.4 \times 25.4 \times 0.8 \\ & \text{(Unit: mm)} \end{aligned}$

Fig. 5.1 Device Mounted on a Glass-Epoxy Board (a)

Fig. 5.2 Device Mounted on a Glass-Epoxy Board (b)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



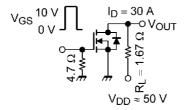
6. Electrical Characteristics

6.1. Static Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I _{GSS}	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±0.1	μА
Drain cut-off current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V	_	_	10	
Drain-source breakdown voltage	V _{(BR)DSS}	I _D = 10 mA, V _{GS} = 0 V	100	_	_	٧
	V _{(BR)DSX}	I _D = 10 mA, V _{GS} = -20 V	65	_	_	
Gate threshold voltage	V_{th}	V _{DS} = 10 V, I _D = 1.0 mA	2.0	_	4.0	
Drain-source on-resistance	R _{DS(ON)}	V _{GS} = 10 V, I _D = 30 A	_	3.7	4.5	mΩ

6.2. Dynamic Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C _{iss}	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz	_	4000	5200	pF
Reverse transfer capacitance	C _{rss}		_	31	63	
Output capacitance	C _{oss}		_	700	_	
Gate resistance	r _g	-	_	1.0	1.5	Ω
Switching time (rise time)	t _r	See Figure 6.2.1.	_	9.6	_	ns
Switching time (turn-on time)	t _{on}		_	25	_	
Switching time (fall time)	t _f]	_	13	_	
Switching time (turn-off time)	t _{off}		_	52		



Duty \leq 1%, $t_{\text{W}}=10~\mu\text{s}$

Fig. 6.2.1 Switching Time Test Circuit

6.3. Gate Charge Characteristics (T_a = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Q_g	$V_{DD} \approx 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 60 \text{ A}$	1	58	1	nC
Gate-source charge 1	Q _{gs1}			22		
Gate-drain charge	Q_{gd}		_	12		
Gate switch charge	Q_SW		_	22	_	

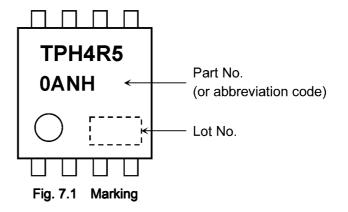
6.4. Source-Drain Characteristics (T_a = 25°C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (pulsed) ((Note 6)	I_{DRP}	_		_	200	Α
Diode forward voltage		V_{DSF}	I _{DR} = 60 A, V _{GS} = 0 V		_	-1.2	V

Note 6: Ensure that the channel temperature does not exceed 150°C.



7. Marking





8. Characteristics Curves (Note)

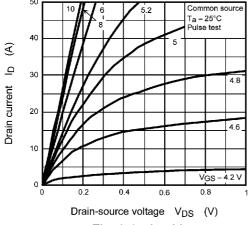
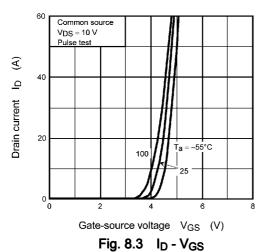


Fig. 8.1 $I_D - V_{DS}$



Puise lest

Puise lest

ADS(ON)

ADS(ON

Common source

Ta = 25°C

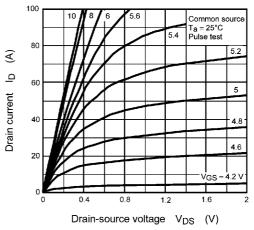


Fig. 8.2 I_D - V_{DS}

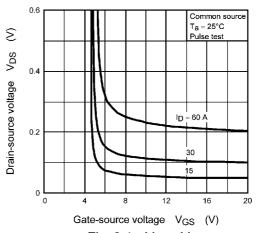


Fig. 8.4 V_{DS} - V_{GS}

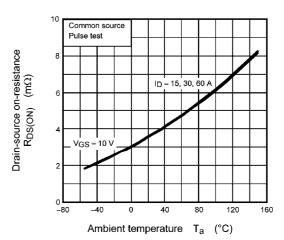


Fig. 8.6 R_{DS(ON)} - T_a

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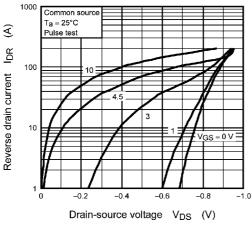


Fig. 8.7 I_{DR} - V_{DS}

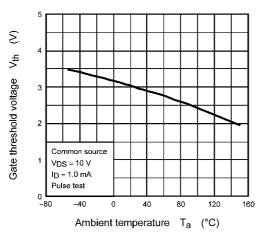


Fig. 8.9 V_{th} - T_a

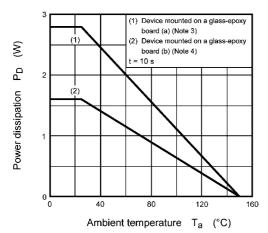


Fig. 8.11 P_D - T_a (Guaranteed Maximum)

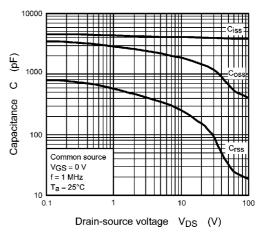


Fig. 8.8 Capacitance - V_{DS}

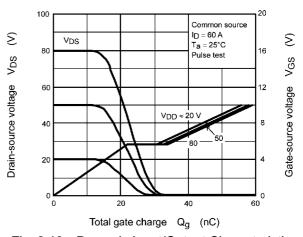


Fig. 8.10 Dynamic Input/Output Characteristics

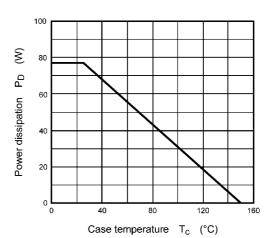


Fig. 8.12 P_D - T_c (Guaranteed Maximum)



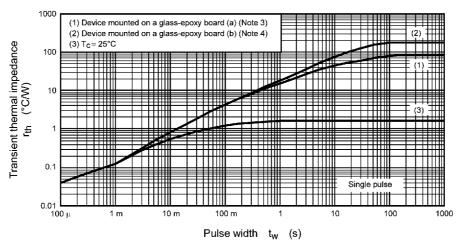


Fig. 8.13 r_{th} - t_w (Guaranteed Maximum)

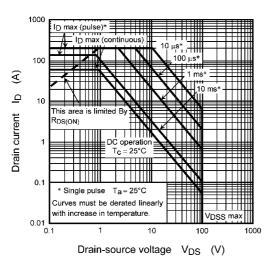


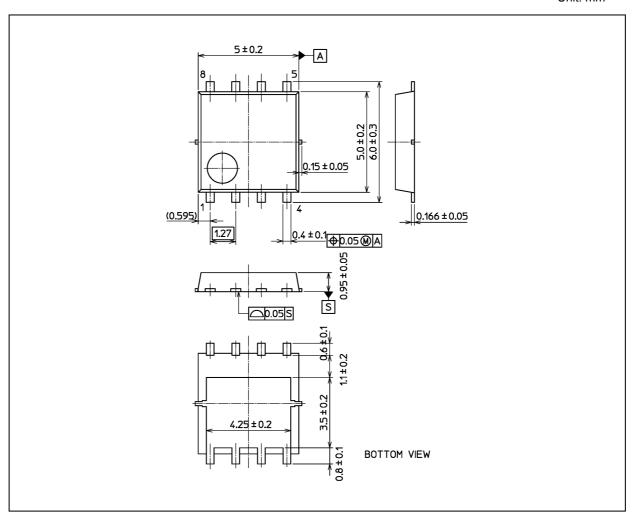
Fig. 8.14 Safe Operating Area (Guaranteed Maximum)

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



Package Dimensions

Unit: mm



The package can be selected according to your preference. For details, please contact your TOSHIBA sales representative.

Weight: 0.087 g (typ.)

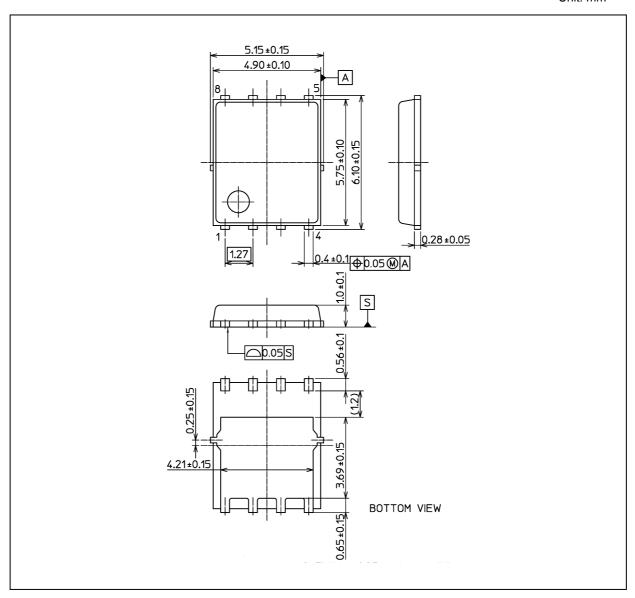
	Package Name(s)
TOSHIBA: 2-5Q1S	
Nickname: SOP Advance	

Rev.4.0



Package Dimensions

Unit: mm



The package can be selected according to your preference. For details, please contact your TOSHIBA sales representative.

Weight: 0.111 g (typ.)

Package Name(s)
TOSHIBA: 2-5W1A
Nickname: SOP Advance(N)



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